

eMD-SmartMotion_ICM20948 Software Release Notes



CONTENTS

Overview	3
Supported Sensors	-
Software Modules Included	
Supported Features	
Resolved Issues	
Known Issues	
Test Platform	4
Notes	4
Compliance Declaration Disclaimer	



OVERVIEW

This document details the relevant information regarding the eMD-SmartMotion_ICM20948-1.1.1 software release.

SUPPORTED SENSORS

- ICM20948

SOFTWARE MODULES INCLUDED

The eMD-SmartMotion package includes all the necessary files to create a custom application for any of the supported ICM sensors (see above).

The package is organized as follow

- doc: Document(s) describing the use of this firmware development platform.
- **EMD-App:** contains sample firmware source and project files.
 - o src:
- At the top level: Shared .c & .h files.
- ASF: Shared Atmel system files.
- config: Shared config files.
- ICM*: Sensor specific files, main.[c,h], sensor.[c,h] and system.[c,h].
- o *.cproj: AtmelStudio project file for the supported sensor.
- **EMD-Core:** Contains TDK driver files. These files are built into an archive libEMD-Core-ICM*.a. Each supported sensor has its own .a file.
 - config: The Makefile(s) used to create the sensor driver archives.
 - sources/Invn: TDK libraries source files.
 - *.cproj: AtmelStudio project files for each of the supported sensors.
- scripts Batch files for building and flashing release versions of the firmware for each sensor.
- **tools** The files required to run the host application sensor-cli.
- EMD-G55-ICM*.atsIn Atmel Studio solution files for each of the supported sensors.
- release Contains precompiled elf and binary files

SUPPORTED FEATURES

Sensor features supported:

- Raw accelerometer
- Raw Gyroscope
- Calibrated accelerometer
- Calibrated gyroscope
- Uncalibrated gyroscope
- Game rotation vector
- Gravity
- Linear Acceleration

Optional sensor features supported:

- Calibrated magnetometer (AKM9916 only)
- Uncalibrated magnetometer
- Rotation vector
- Geomagnetic rotation vector
- Step Detector
- Step Counter
- Tilt Detector
- Pick-Up Gesture
- BAC (Activity Classifier)

Document Number: AN-XXX Revision: 1.0 Date: 03/22/2018



- B2S
- SMD

RESOLVED ISSUES

- [CUS-3563] End customer report gyro output become strange for ICM-20948/DMP
- [ESM-153] GRV convergence takes long

KNOWN ISSUES

- SPI clock interface speed should not be set higher than 2.5MHz to ensure sensor data consistency
- SMD detection for running like motion has not been supported
- Occasional Time-stamp jitter observed during stress-test Occasionally, accelerometer data in wrong rate and/or no magnetometer data have been seen after many iteration of command sequences like, set odr, enable-disable continuous and non-continuous sensors. This unexpected system behavior has been seen during stress-test, only for SPI configuration on SmartMotion platform (Atmel G55 based). The state can be recovered by restarting the sensor-cli application (resets the device in software) or resetting the device manually. The issue has not been seen for SmartMotion I2C interface or other MCU platforms using SPI interface.

TEST PLATFORM

This section describes the software test platform used during the test

Software Component		
Package	eMD-SmartMotion_ICM20948-1.1.1	
Host	Windows 7	
Hardware Component		
eMD Platform	SmartMotion board with onboard	
	ICM20048	

NOTES

ICM20948:

This release provides standalone example applications that run on the eMD-SmartMotion platform only. A host application, sensor-cli, that runs on a Windows PC and communicates with the eMD-SmartMotion firmware through a TDK transport protocol is included within this release.

Document Number: AN-XXX Revision: 1.0 Date: 03/22/2018



COMPLIANCE DECLARATION DISCLAIMER

InvenSense believes the environmental and other compliance information given in this document to be correct but cannot guarantee accuracy or completeness. Conformity documents substantiating the specifications and component characteristics are on file. InvenSense subcontracts manufacturing and the information contained herein is based on data received from vendors and suppliers, which has not been validated by InvenSense.

This information furnished by InvenSense is believed to be accurate and reliable. However, no responsibility is assumed by InvenSense for its use, or for any infringements of patents or other rights of third parties that may result from its use. Specifications are subject to change without notice. InvenSense reserves the right to make changes to this product, including its circuits and software, in order to improve its design and/or performance, without prior notice. InvenSense makes no warranties, neither expressed nor implied, regarding the information and specifications contained in this document. InvenSense assumes no responsibility for any claims or damages arising from information contained in this document, or from the use of products and services detailed therein. This includes, but is not limited to, claims or damages based on the infringement of patents, copyrights, mask work and/or other intellectual property rights.

Certain intellectual property owned by InvenSense and described in this document is patent protected. No license is granted by implication or otherwise under any patent or patent rights of InvenSense. This publication supersedes and replaces all information previously supplied. Trademarks that are registered trademarks are the property of their respective companies. InvenSense sensors should not be used or sold in the development, storage, production or utilization of any conventional or mass-destructive weapons or for any other weapons or life threatening applications, as well as in any other life critical applications such as medical equipment, transportation, aerospace and nuclear instruments, undersea equipment, power plant equipment, disaster prevention and crime prevention equipment.

©2016 InvenSense, Inc. All rights reserved. InvenSense, MotionTracking, MotionProcessing, MotionProcessor, MotionFusion, MotionApps, DMP, AAR, and the InvenSense logo are trademarks of InvenSense, Inc. Other company and product names may be trademarks of the respective companies with which they are associated.



©2016 InvenSense, Inc. All rights reserved.

Document Number: AN-XXX Revision: 1.0 Date: 03/22/2018